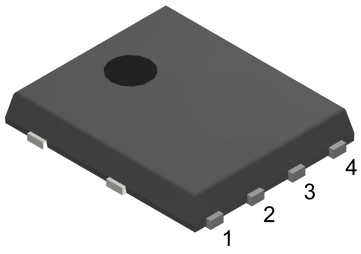
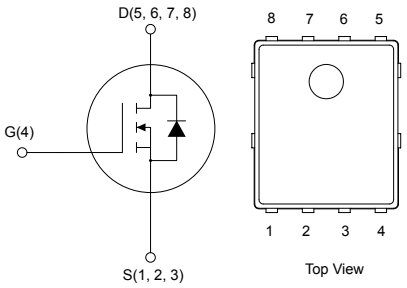
N-channel 100 V, 5 mΩ typ., 107 A, STripFET™ F7 Power MOSFET in a PowerFLAT™ 5x6 package



PowerFLAT™ 5x6



Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D	P_{TOT}
STL110N10F7	100 V	6 mΩ	107 A	136 W

- Among the lowest $R_{DS(on)}$ on the market
- Excellent FoM (figure of merit)
- Low C_{rss}/C_{iss} ratio for EMI immunity
- High avalanche ruggedness

Applications

- Switching applications

Description

This N-channel Power MOSFET utilizes STripFET™ F7 technology with an enhanced trench gate structure that results in very low on-state resistance, while also reducing internal capacitance and gate charge for faster and more efficient switching.

Product status link
STL110N10F7

Product summary	
Order code	STL110N10F7
Marking	110N10F7
Package	PowerFLAT™ 5x6
Packing	Tape and reel

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	100	V
V_{GS}	Gate-source voltage	±20	V
I_D[(1)]	Drain current (continuous) at T_C = 25 °C	107	A
	Drain current (continuous) at T_C = 100 °C	75	A
I_{DM}[(1)(2)]	Drain current (pulsed)	428	A
I_D[(3)]	Drain current (continuous) at T_C = 25 °C	21	A
	Drain current (continuous) at T_C=100 °C	14	A
I_{DM}[(2)(3)]	Drain current (pulsed)	84	A
P_{TOT}[(1)]	Total dissipation at T_C = 25 °C	136	W
P_{TOT}[(3)]	Total dissipation at T_{pcb} = 25 °C	4.8	W
E_{AS}[(4)]	Single pulse avalanche energy	490	mJ
T_J	Operating junction temperature range	-55 to 175	°C
T_{stg}	Storage temperature range		

1. *This value is rated according to $R_{thj\text{-}c}$.*
2. *Pulse width limited by safe operating area.*
3. *This value is rated according to $R_{thj\text{-}pcb}$.*
4. *Starting T_J = 25 °C, I_D = 18 A, V_{DD} = 50 V*

Table 2. Thermal resistance

Symbol	Parameter	Value	Unit
$R_{thj\text{-}case}$	Thermal resistance junction-case	1.1	°C/W
$R_{thj\text{-}pcb}$[(1)]	Thermal resistance junction-pcb	31.3	°C/W

1. *When mounted on an FR-4 board of 1 inch², 2oz Cu, t < 10 s.*

2 Electrical characteristics

(T_{CASE} = 25 °C unless otherwise specified)

Table 3. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS} = 0 V, I_D = 250 µA	100			V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 100 V			1	µA
		V_{GS} = 0 V, V_{DS} = 100 V, T_C = 125 °C(1)			10	
I_{GSS}	Gate body leakage current	V_{DS} = 0, V_{GS} = 20 V			100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	2.5		4.5	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D= 10 A		5	6	mΩ

1. *Defined by design, not subject to production test.*

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS} = 50 V, f = 1 MHz, V_{GS} = 0 V	-	5117	-	pF
C_{oss}	Output capacitance		-	992	-	
C_{rss}	Reverse transfer capacitance		-	39	-	
Q_g	Total gate charge	V_{DD} = 50 V, I_D = 21 A, V_{GS} = 0 to 10 V (see Figure 15. Test circuit for gate charge behavior	-	72	-	nC
Q_{gs}	Gate-source charge		-	30	-	
Q_{gd}	Gate-drain charge		-	17	-	

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 50 V, I_D = 10 A, R_G = 4.7 Ω, V_{GS} = 10 V (see Figure 14. Test circuit for resistive load switching times and Figure 19. Switching time waveform)	-	25	-	ns
t_r	Rise time		-	36	-	ns
$t_{d(off)}$	Turn-off delay time		-	52	-	ns
t_f	Fall time		-	21	-	ns

Table 6. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{SD}(1)	Forward on voltage	I_{SD} = 21 A, V_{GS} = 0 V	-		1.2	V
t_{rr}	Reverse recovery time	I_{SD} = 21 A, di/dt = 100 A/µs, V_{DD} = 80 V, T_j = 150 °C (see Figure 16. Test circuit for inductive load switching and diode recovery times)	-	77		ns
Q_{rr}	Reverse recovery charge		-	150		nC
I_{RRM}	Reverse recovery current		-	4.3		A

1. *Pulsed: pulse duration = 300 µs, duty cycle 1.5%*

2.1 Electrical characteristics (curves)

Figure 3. Safe operating area

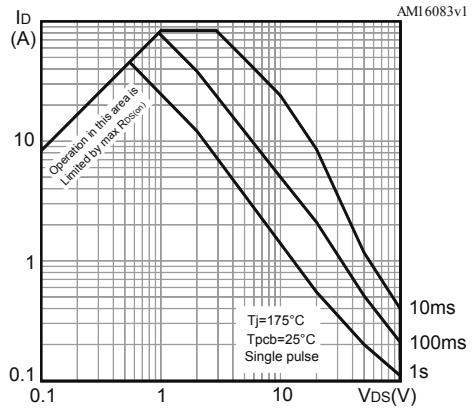


Figure 4. Thermal impedance

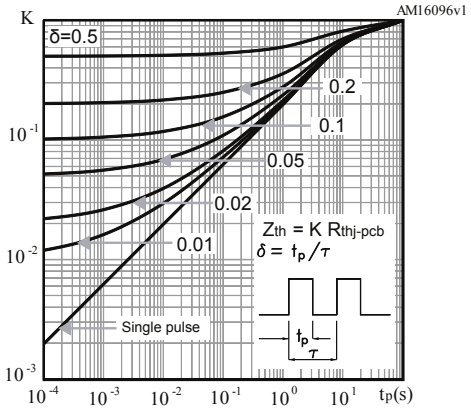


Figure 5. Output characteristics

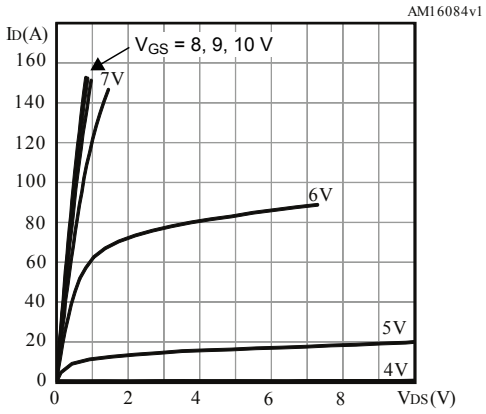


Figure 6. Transfer characteristics

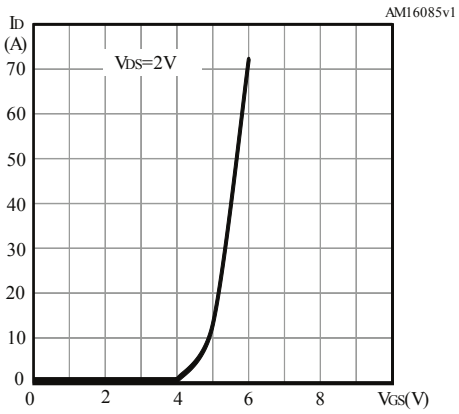


Figure 7. Gate charge vs gate-source voltage

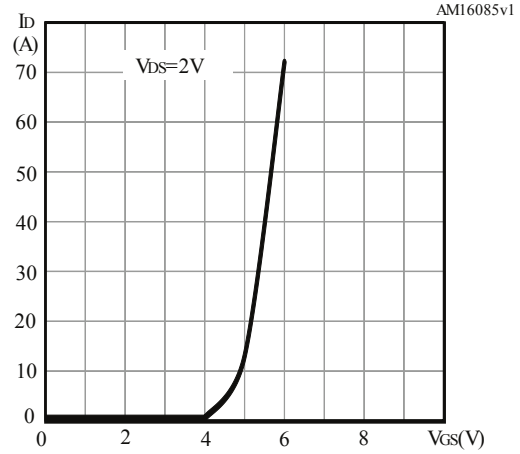


Figure 8. Static drain-source on-resistance

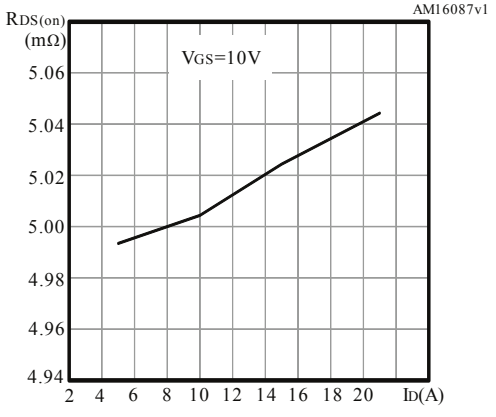


Figure 9. Capacitance variations

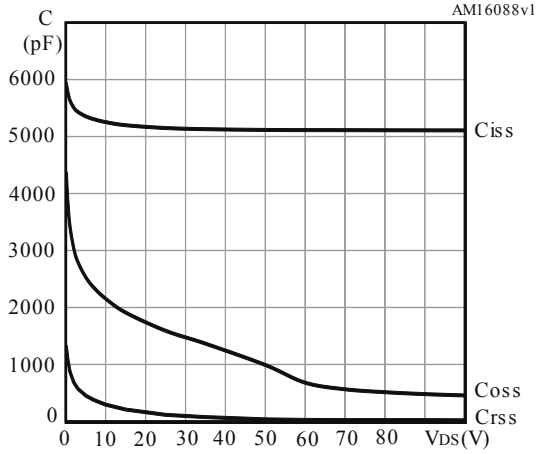


Figure 10. Normalized gate threshold voltage vs temperature

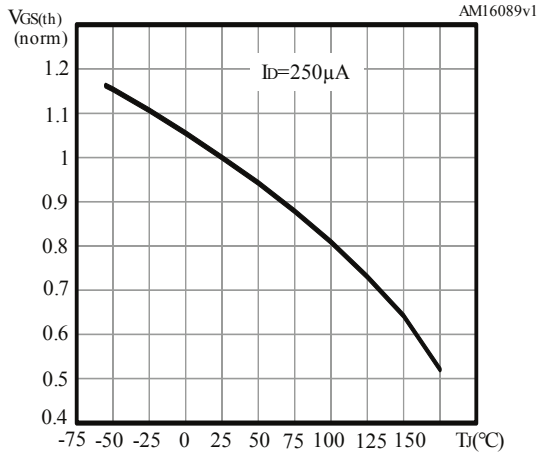


Figure 11. Normalized on-resistance vs temperature

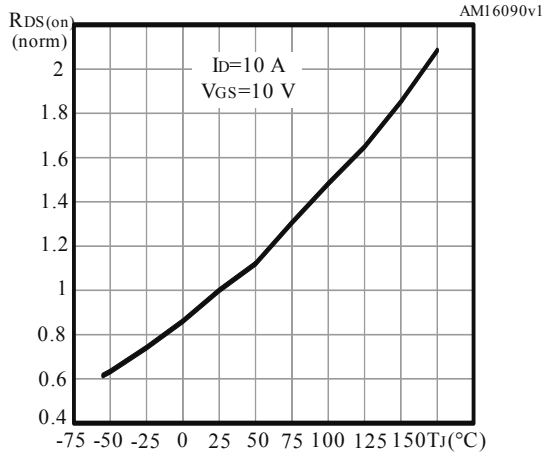


Figure 12. Source-drain diode forward characteristics

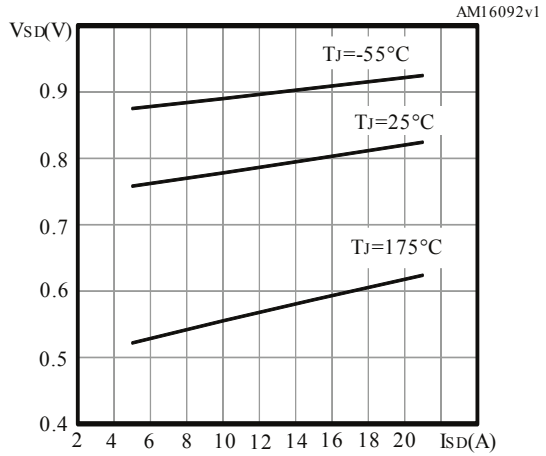
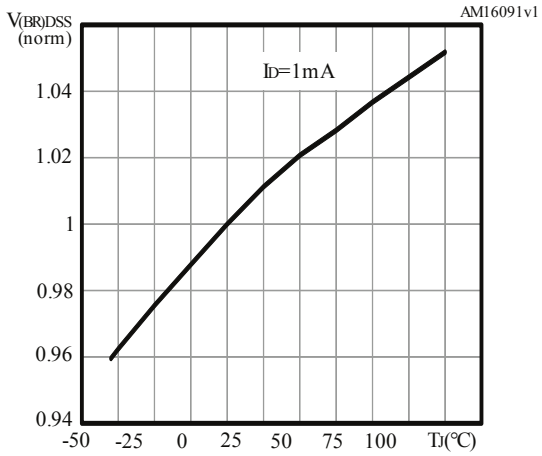


Figure 13. Normalized $V_{(BR)DSS}$ vs temperature



3 Test circuits

Figure 14. Test circuit for resistive load switching times

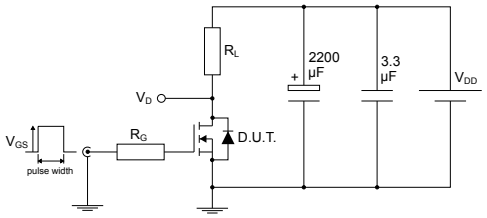


Figure 15. Test circuit for gate charge behavior

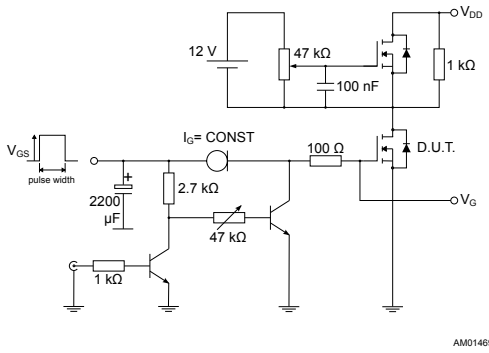


Figure 16. Test circuit for inductive load switching and diode recovery times

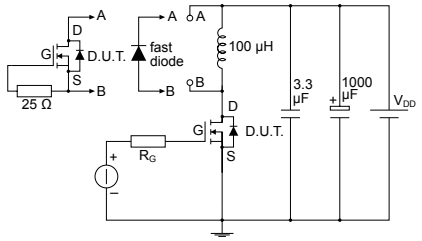


Figure 17. Unclamped inductive load test circuit

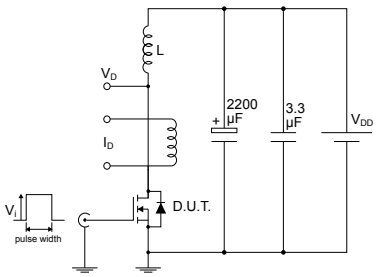


Figure 18. Unclamped inductive waveform

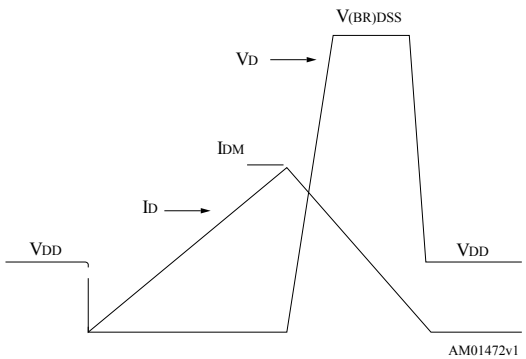
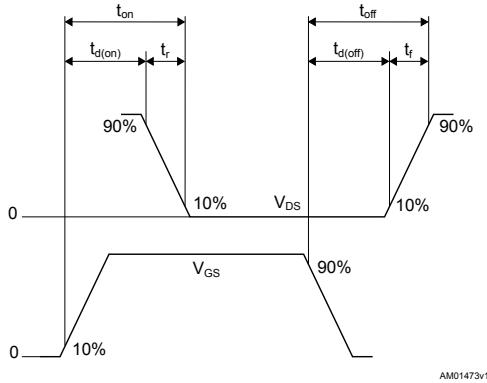


Figure 19. Switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 PowerFLAT™ 5x6 type C package information

Figure 20. PowerFLAT™ 5x6 type C package outline

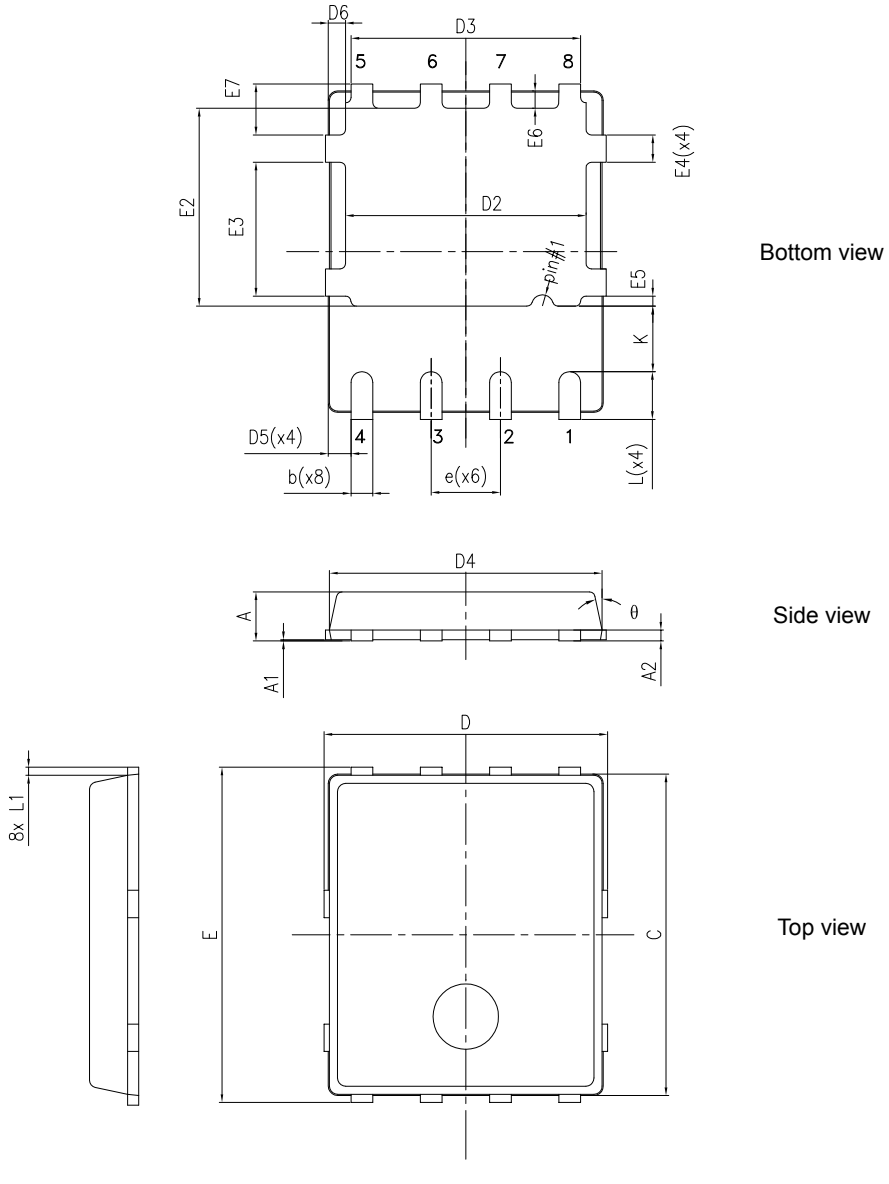
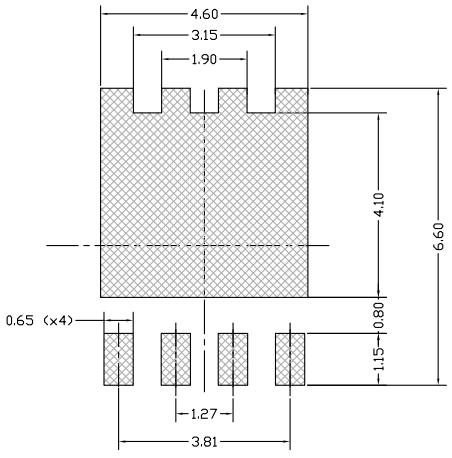


Table 7. **PowerFLAT™ 5x6 type C package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	0.80		1.00
A1	0.02		0.05
A2		0.25	
b	0.30		0.50
C	5.80	6.00	6.20
D	5.00	5.20	5.40
D2	4.15		4.45
D3	4.05	4.20	4.35
D4	4.80	5.00	5.20
D5	0.25	0.40	0.55
D6	0.15	0.30	0.45
e		1.27	
E	5.95	6.15	6.35
E2	3.50		3.70
E3	2.35		2.55
E4	0.40		0.60
E5	0.08		0.28
E6	0.20	0.325	0.45
E7	0.75	0.90	1.05
K	1.05		1.35
L	0.725		1.025
L1	0.05	0.15	0.25
θ	0°		12°

Figure 21. **PowerFLAT™ 5x6 recommended footprint (dimensions are in mm)**



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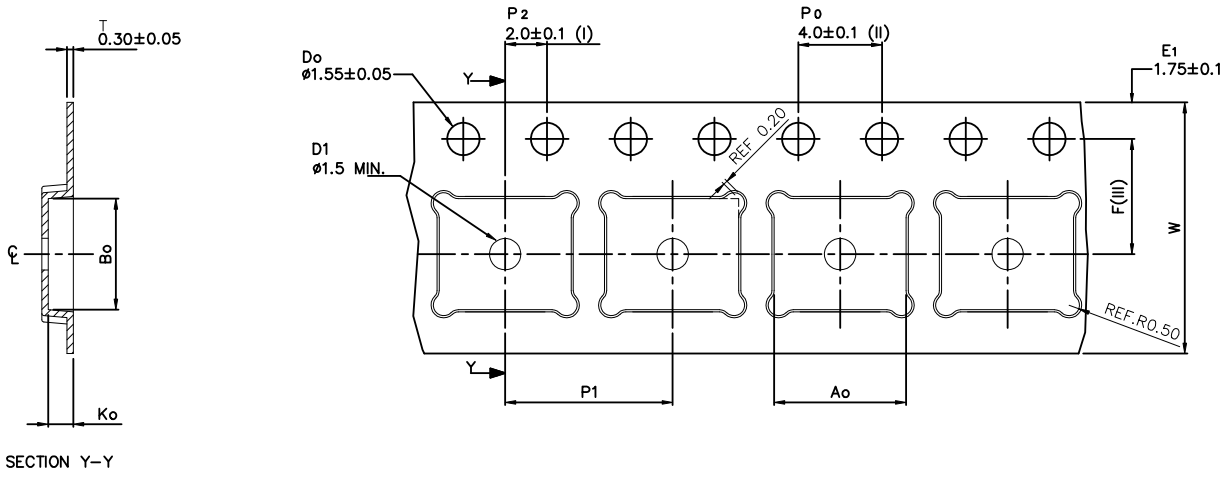
4.2 PowerFLAT™ 5x6 packing information

Figure 22. **PowerFLAT™ 5x6 tape (dimensions are in mm)**



Ao	6.30 +/– 0.1
Bo	5.30 +/– 0.1
Ko	1.20 +/– 0.1
F	5.50 +/– 0.1
P1	8.00 +/– 0.1
W	12.00 +/– 0.3

(I) Measured from centreline of sprocket hole to centreline of pocket.

(II) Cumulative tolerance of 10 sprocket holes is ±0.20.

(III) Measured from centreline of sprocket hole to centreline of pocket

Base and bulk quantity 3000 pcs
All dimensions are in millimeters

8234350_Tape_rev_C

Figure 23. **PowerFLAT™ 5x6 package orientation in carrier tape**

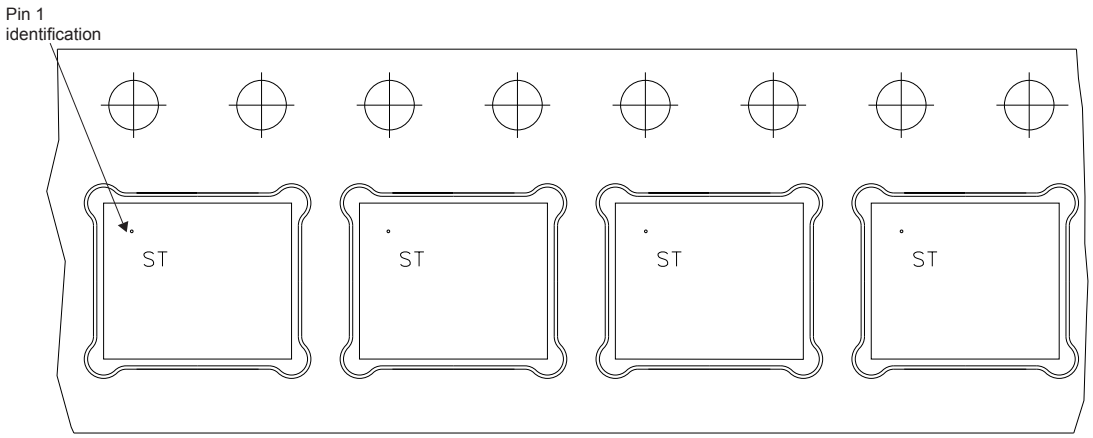
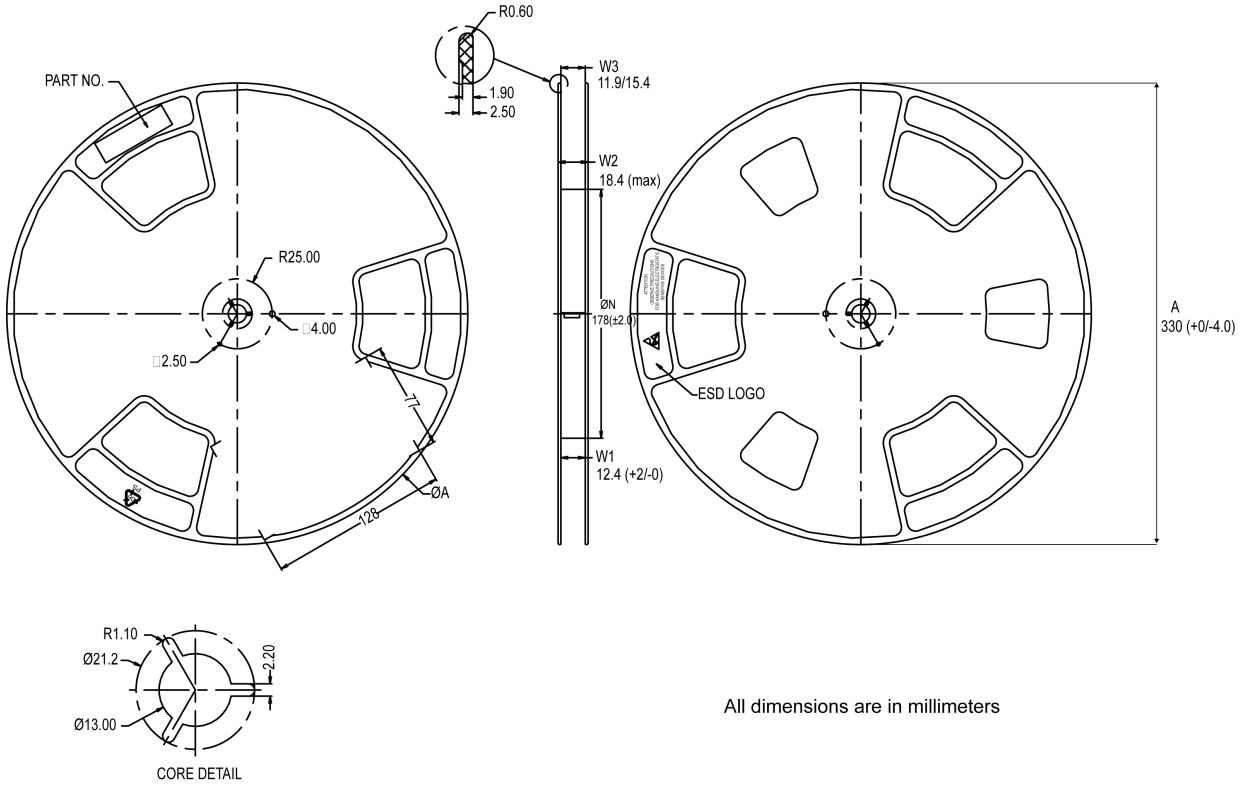


Figure 24. **PowerFLAT™ 5x6 reel**



All dimensions are in millimeters

8234350_Reel_rev_C

Revision history

Table 8. Document revision history

Date	Revision	Changes
03-Dec-2012	1	First release.
12-Dec-2013	2	Modified: P_{TOT} value and *Figure 1* in cover page Modified: I_D, I_{DM} and P_{TOT} values in *Table 2* Added: E_{AS} value in *Table 2* Modified: all values in *Table 3* Modified: I_{DSS}, I_{GSS} and I_D for $R_{DS(on)}$ Updated: the entire typical values in *Table 5, 6* and *7* Updated: *Figure 13, 14, 15* and *16* Minor text changes
25-Mar-2014	3	Updated title and features on cover page. Added P_{TOT} value at T_C = 25 °C in *Table 2: Absolute maximum ratings*. Updated *Section 4: Package mechanical data*.
20-Aug-2014	4	Modified: title, features and description Modified: *Figure 2* and *3* Updated: *Section 4: Package mechanical data*. Minor text changes
17-Sep-2018	5	Removed maturity status indication. Updated title and description on cover page. Updated Table 1. Absolute maximum ratings and Table 6. Source-drain diode. Updated Section 4.1 PowerFLAT™ 5x6 type C package information. Minor text changes

Contents

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